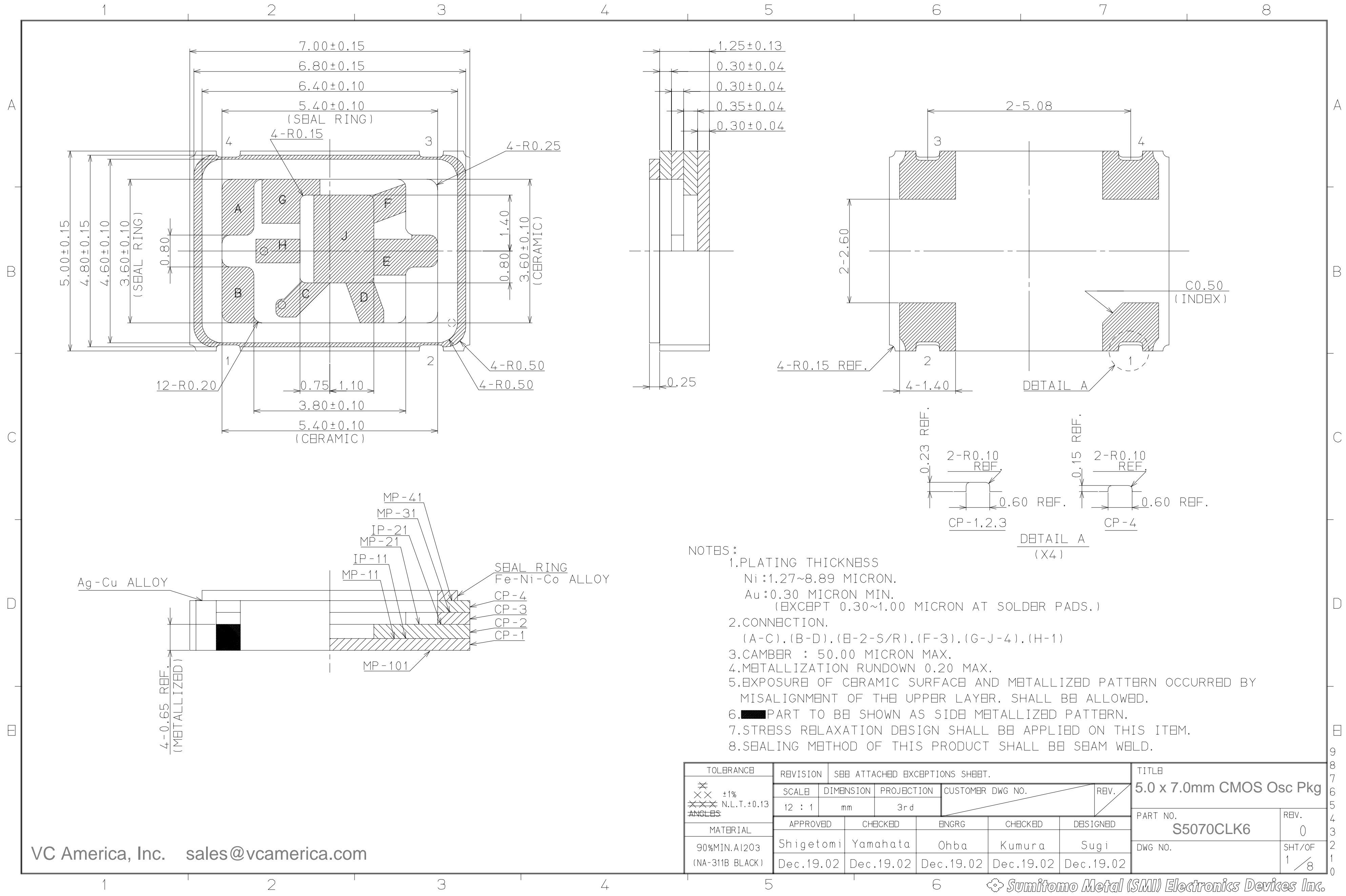

NOTES:

1. PLATING THICKNESS
   Ni: 1.27~8.89 MICRON.
   Au: 0.30 MICRON MIN.
   (EXCEPT 0.30~1.00 MICRON AT SOLDER PADS.)
2. CONNECTION.
   (A-C),(B-D),(E-2-S/R),(F-3),(G-J-4),(H-1)
3. CAMBER : 50.00 MICRON MAX.
4. METALLIZATION RUNDOWN 0.20 MAX.
5. EXPOSURE OF CERAMIC SURFACE AND METALLIZED PATTERN OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
6. ▬ PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
7. STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
8. SEALING METHOD OF THIS PRODUCT SHALL BE SEAM WELD.

TOLERANCE	REVISION	SEE ATTACHED EXCEPTIONS SHEET.				TITLE
X ±1%, XX, XXX N.L.T.±0.13, ANGLES	SCALE 12 : 1	DIMENSION mm	PROJECTION 3rd	CUSTOMER DWG NO.	REV.	5.0 x 7.0mm CMOS Osc Pkg
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	PART NO. S5070CLK6 / REV. 0
90%MIN.AI203	Shigetomi	Yamahata	Ohba	Kumura	Sugi	DWG NO.
(NA-311B BLACK)	Dec.19.02	Dec.19.02	Dec.19.02	Dec.19.02	Dec.19.02	SHT/OF 1/8

VC America, Inc. sales@vcamerica.com

Sumitomo Metal (SMI) Electronics Devices Inc.